

WEST Search History

Hide Items

Restore

Clear

Cancel

DATE: Tuesday, April 27, 2004

Hide?	<u>Set</u> <u>Name</u>	<u>Query</u>	<u>Hit</u> <u>Coun</u>
	<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=OR</i>		
<input type="checkbox"/>	L1	(bump with connect\$3 with pad) and ((damag\$3 or deform\$6) with bump) and ((known adj good) or KGD)	

END OF SEARCH HISTORY



IEEE Xplore®

RELEASE 1.6

Welcome
United States Patent and Trademark Office

IEEE Xplore
1 Million Documents
1 Million Users
...And Growing
» Search Results

[Help](#) [FAQ](#) [Terms](#) [IEEE Peer Review](#)
[Quick Links](#)

Welcome to IEEE Xplore®

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

Search

- ☐ By Author
- ☐ Basic
- ☐ Advanced

Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

Your search matched **20** of **1027552** documents.

A maximum of **500** results are displayed, **15** to a page, sorted by **Relevance** in **Descending** order.

Refine This Search:

You may refine your search by editing the current search expression or entering a new one in the text box.

☐ Check to search within this result set

Results Key:

JNL = Journal or Magazine **CNF** = Conference **STD** = Standard

1 Integrated flow-thermomechanical and reliability analysis of a densely packed C4/CBGA assembly

Hong, B.Z.; Yuan, T.-D.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 1998. ITherm '98. The Sixth Intersociety Conference on , 27-30 May 1998
Pages:220 - 228

[\[Abstract\]](#) [\[PDF Full-Text \(876 KB\)\]](#) IEEE CNF

2 Flip-chip interconnection technology for advanced thermal conduction modules

Ray, S.K.; Beckham, K.; Master, R.;

Electronic Components and Technology Conference, 1991. Proceedings., 41st , 11-16 May 1991
Pages:772 - 778

[\[Abstract\]](#) [\[PDF Full-Text \(544 KB\)\]](#) IEEE CNF

3 FCOB reliability evaluation simulating multiple rework/reflow processes

Wayne Chen;

Components, Packaging, and Manufacturing Technology, Part C, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on] , Volume: 19 , Issue: 4 , Oct. 1996
Pages:270 - 276

[\[Abstract\]](#) [\[PDF Full-Text \(188 KB\)\]](#) IEEE JNL

4 A hi-density C4/CBGA interconnect technology for a CMOS micr process r

Kromann, G.B.; Gerke, R.D.; Wayne Wei-Xi Huang;

Components, Packaging, and Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on] , Volume: 19 , Issue: 1 , Feb. 1996

Pages:166 - 173

[\[Abstract\]](#) [\[PDF Full-Text \(1256 KB\)\]](#) IEEE JNL

5 Effect of package design and layout on BGA solder joint reliability of an organic C4 package

Chandran, B.; Goyal, D.; Thomas, J.;

Electronic Components and Technology Conference, 2000. 2000 Proceedings.

50th , 21-24 May 2000

Pages:1205 - 1214

[\[Abstract\]](#) [\[PDF Full-Text \(936 KB\)\]](#) IEEE CNF

6 Low-cost ceramic thin-film ball grid arrays

Panicker, M.P.R.; Greenman, N.L.; Forster, J.; Johnston, P.;

Electronic Components and Technology Conference, 1994. Proceedings., 44th , 1-4 May 1994

Pages:29 - 31

[\[Abstract\]](#) [\[PDF Full-Text \(236 KB\)\]](#) IEEE CNF

7 FCOB reliability evaluation simulating multiple rework/reflow processes

Chen, W.; Gentile, J.; Higgins, L.;

Electronic Components and Technology Conference, 1996. Proceedings., 46th , 28-31 May 1996

Pages:1184 - 1195

[\[Abstract\]](#) [\[PDF Full-Text \(1704 KB\)\]](#) IEEE CNF

8 Device interconnection technology for advanced thermal conduction modules

Ray, S.K.; Beckham, K.F.; Master, R.N.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C] , Volume: 15 , Issue: 4 , Aug. 1992

Pages:432 - 437

[\[Abstract\]](#) [\[PDF Full-Text \(584 KB\)\]](#) IEEE JNL

9 CBGA and C4 fatigue dependence on thermal cycle frequency

Di Giacomo, G.; Ahmed, U.;

Advanced Packaging Materials: Processes, Properties and Interfaces, 2000. Proceedings. International Symposium on , 6-8 March 2000

Pages:261 - 264

[\[Abstract\]](#) [\[PDF Full-Text \(276 KB\)\]](#) IEEE CNF

10 Design-based thermal simulation methodology for ball grid array packages

Johnson, Z.; Eyman, M.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 1998. ITherm '98. The Sixth Intersociety Conference on , 27-30 May 1998

Pages:82 - 87

[\[Abstract\]](#) [\[PDF Full-Text \(520 KB\)\]](#) IEEE CNF

11 A low-cost ceramic BGA package for 50 Gb/s multiplexing circuit

Shan, L.; Trehwella, J.; Baks, C.; John, R.; Dyckman, W.; O'Connor, D.; Pillai, E.;
 Electrical Performance of Electronic Packaging, 2003 , 27-29 Oct. 2003
 Pages:59 - 62

[\[Abstract\]](#) [\[PDF Full-Text \(386 KB\)\]](#) IEEE CNF

12 Thermal deformation analysis in flip-chip packages using high resolution moire interferometry

Guotao Wang; Jie-Hua Zhao; Min Ding; Ho, P.S.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 2002. ITherm 2002. The Eighth Intersociety Conference on , 30 May-1 June 2002
 Pages:869 - 875

[\[Abstract\]](#) [\[PDF Full-Text \(1180 KB\)\]](#) IEEE CNF

13 Modified flip-chip attach process using high performance non-flow underfill paste

Hatano, C.; Takahashi, H.; Ichida, T.;

Electronic Components and Technology Conference, 2002. Proceedings. 52nd , 28-31 May 2002
 Pages:398 - 403

[\[Abstract\]](#) [\[PDF Full-Text \(1184 KB\)\]](#) IEEE CNF

14 Performance of evaporated and plated bumps on organic substrates

Mistry, A.; Czarnowski, J.; Beddingfield, C.; Tan, Q.; Guajardo, J.; Rhyner, K.; Kleffner, J.; Scanlon, T.; Lozano, J.; Wontor, D.; Scott, K.;

Electronics Manufacturing Technology Symposium, 1998. Twenty-Third IEEE/CPMT , 19-21 Oct. 1998
 Pages:1 - 7

[\[Abstract\]](#) [\[PDF Full-Text \(722 KB\)\]](#) IEEE CNF

15 ITherm'98. Sixth Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (Cat. No.98CH36208)

Thermal and Thermomechanical Phenomena in Electronic Systems, 1998. ITherm '98. The Sixth Intersociety Conference on , 27-30 May 1998

[\[Abstract\]](#) [\[PDF Full-Text \(472 KB\)\]](#) IEEE CNF

[1](#) [2](#) [Next](#)